



US 20240244984A1

(19) **United States**

(12) **Patent Application Publication**
LARA-AVILA et al.

(10) **Pub. No.: US 2024/0244984 A1**

(43) **Pub. Date: Jul. 18, 2024**

(54) **ELECTRICAL CONTACTS FOR LOW
DIMENSIONAL MATERIALS**

Publication Classification

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(51) **Int. Cl.**
H10N 52/80 (2023.01)
C01B 32/194 (2017.01)
G01R 33/07 (2006.01)
H10N 52/01 (2023.01)
B82Y 15/00 (2011.01)
B82Y 40/00 (2011.01)
H10N 52/00 (2023.01)

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(52) **U.S. Cl.**
CPC **H10N 52/80** (2023.02); **C01B 32/194**
(2017.08); **G01R 33/07** (2013.01); **H10N**
52/01 (2023.02); **B82Y 15/00** (2013.01); **B82Y**
40/00 (2013.01); **C01B 2204/22** (2013.01);
H10N 52/101 (2023.02)

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(21) Appl. No.: **18/619,831**

(57) **ABSTRACT**

(22) Filed: **Mar. 28, 2024**

The present invention relates to a method for connecting an electrical contact to a nanomaterial carried by a substrate. At least one layer of soluble lithography resist is provided on the nanomaterial. An opening in the at least one layer of resist exposes a surface portion of the nanomaterial. At least a portion of the exposed surface portion of the nanomaterial is removed to thereby expose the underlying substrate and an edge of the nanomaterial. A metal is deposited on at least the edge of the nanomaterial and the exposed substrate such that the metal forms an electrical contact with the nanomaterial. Removing at least a portion of the soluble lithography resist from the nanomaterial such that at least a portion of the two-dimensional material is exposed.

Related U.S. Application Data

(63) Continuation of application No. 17/044,504, filed on Oct. 1, 2020, now Pat. No. 11,950,515, filed as application No. PCT/SE2018/051258 on Dec. 6, 2018.

Foreign Application Priority Data

Apr. 3, 2018 (SE) 1850366-4

